THIN FILM SURFACE MOUNT

Bandpass Filter

ABF-11R8G+

50Ω 10.6 to 13 GHz

KEY FEATURES

- Low Passband Insertion Loss of 1 dB Typ.
- High Rejection of 53 dB Typ.
- Good Return Loss of 16 dB Typ.
- Small Size, 5.59 x 8.13 x 2.03 mm



Generic photo used for illustration purposes only

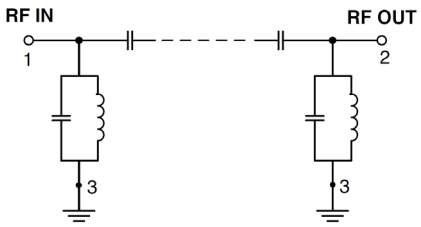
APPLICATIONS

- X-Band Radar
- Test and Measurements

PRODUCT OVERVIEW

Mini-Circuits' Surface Mount Thin-Film filters offer low insertion loss and high rejection realized via Thin-Film on Alumina substrate, using a sputtering process that can guarantee an enhanced Q and repeatable performance. Low pass, high pass, and bandpass surface mount thin-film designs can be realized with this technology up to 40 GHz in a small form factor helping customers achieve their SWaP objectives. Using our high quality thin-film manufacturing process we can guarantee repeatability on large batches of filters.

FUNCTIONAL DIAGRAM

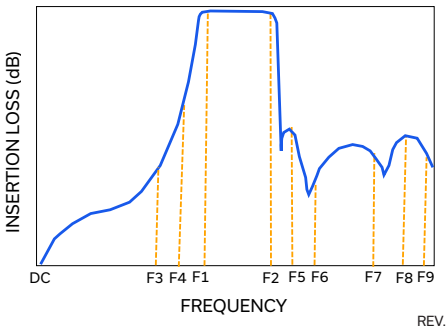


ELECTRICAL SPECIFICATIONS[1,2,3] AT +25°C

Parameter		F#	Frequency (GHz)	Min.	Typ.	Max.	Units
Pass Band	Center Frequency[4]	—	—	—	11.8	—	GHz
	Insertion Loss	F1-F2	10.6 - 13	—	1	1.8	dB
	Return Loss	F1-F2	10.6 - 13	—	16	—	dB
Stopband, Lower	Rejection	DC-F3	DC - 7	45	53	—	dB
		F3-F4	7 - 8.4	20	35	—	
Stopband ,Upper	Rejection	F5-F6	15.5 - 16.5	20	48	—	dB
		F6-F7	16.5 - 19.5	33	41	—	
		F7-F8	19.5 - 25	22	30	—	
		F8-F9	25 - 27	—	20	—	

1. Tested on Evaluation Board P/N TB-ABF-11R8G+ with feedline losses removed by normalization of S12 and S21 traces to mesurement of TB thru-line.
2. This filter is bi-directional RF1 and RF2 ports may be interchanged, see S-Parameters for actual performance.
3. This component is not intended for use as a DC-blocking circuit element. In applications where DC voltage and/or current is present at either the input or output ports, external DC blocking capacitors are required.
4. Typical variation ±3%.

TYPICAL FREQUENCY RESPONSE AT +25°C



ABSOLUTE MAXIMUM RATINGS[5]

Parameter	Ratings
Operating Temperature	-55°C to +125°C
Storage Temperature	-55°C to +125°C
Input Power[6]	8.75 W Max. at 25°C

5. Permanent damage may occur if any of these limits are exceeded.
6. Power rating applies only to signals within the passband. Derated power at +125°C is 3.3 W

REV. OR
ECO-024893
ABF-11R8G+
EDU4857
URJ
250318

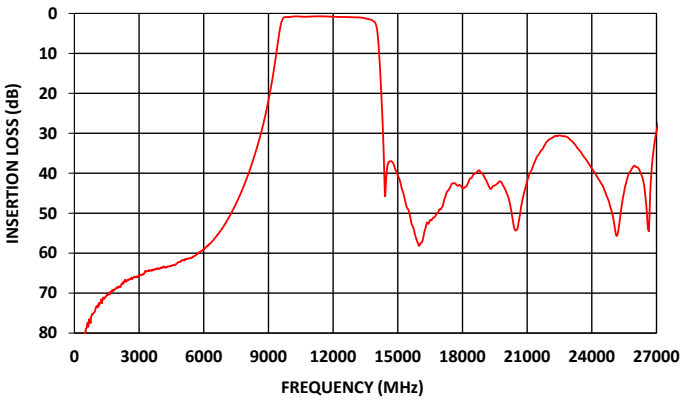
Bandpass Filter

ABF-11R8G+

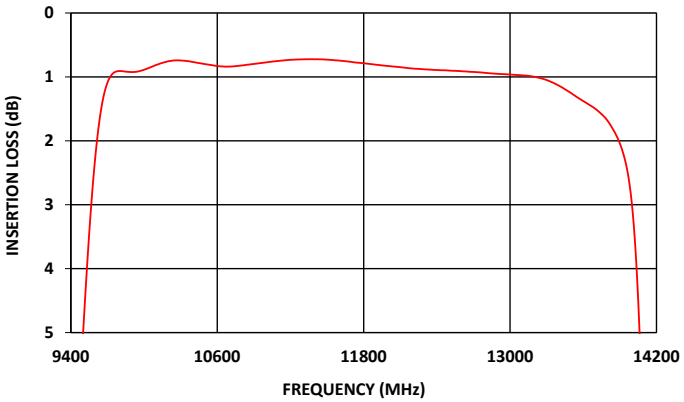
50Ω 10.6 to 13 GHz

TYPICAL PERFORMANCE GRAPHS AT +25°C

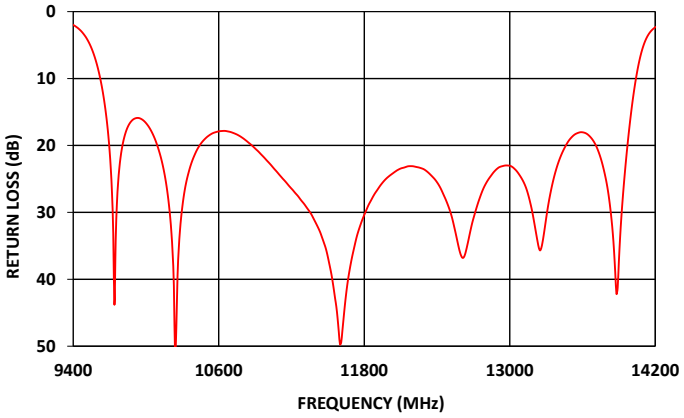
ABF-11R8G+
INSERTION LOSS



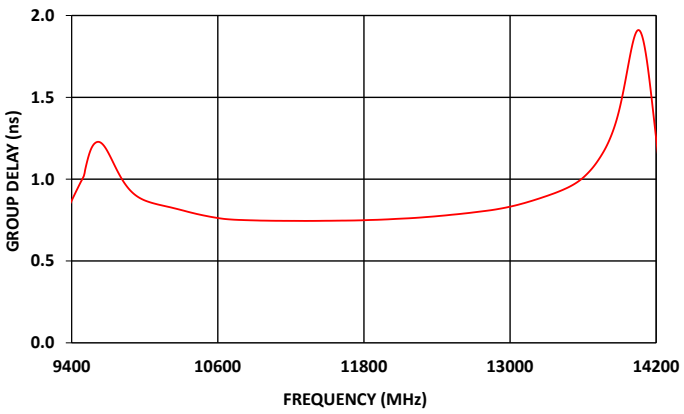
ABF-11R8G+
INSERTION LOSS (Zoomed)



ABF-11R8G+
RETURN LOSS



ABF-11R8G+
GROUP DELAY



THIN FILM SURFACE MOUNT

Bandpass Filter

ABF-11R8G+

50Ω 10.6 to 13 GHz

FUNCTIONAL DIAGRAM

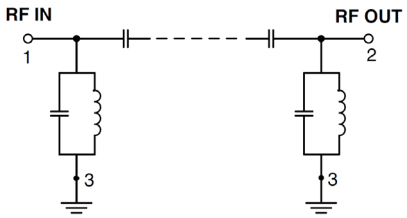
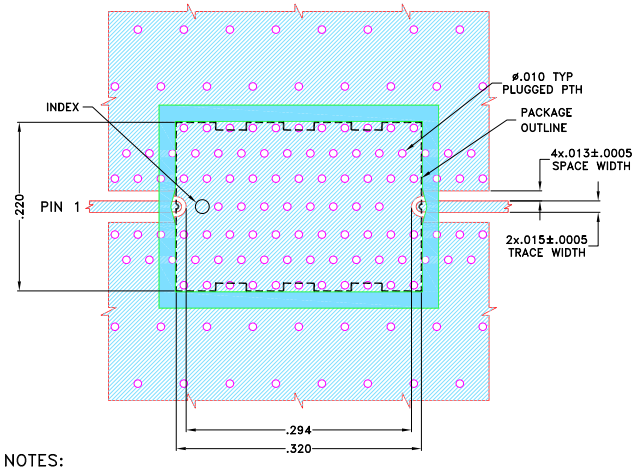


Figure 1. ABF-11R8G+ Functional Diagram

PAD DESCRIPTION

Function	Pad Number	Description
RF1[2]	1	Connects to RF Input Port
RF2[2]	2	Connects to RF Output Port
GROUND	3	Connects to Ground on PCB, (See drawing PL-764)
NC	—	No connection, not used internally. See drawing PL-764 for connection to PCB

SUGGESTED PCB LAYOUT (PL-764)

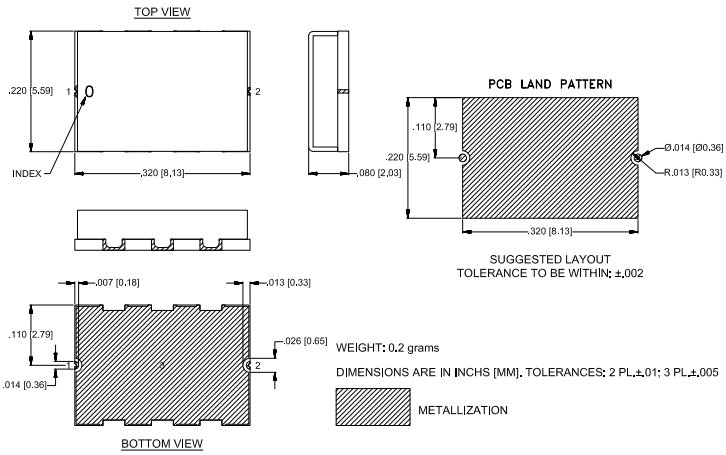


NOTES:
1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (RO4350B Lo Pro) WITH DIELECTRIC THICKNESS .0073±.0007. COPPER: 1/2 Oz. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)
DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

Figure 2. Suggested PCB Layout PL-764

CASE STYLE DRAWING



PRODUCT MARKING*: ABF-11R8G

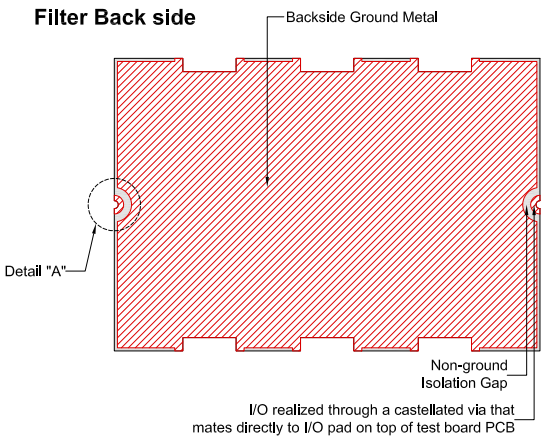
*Marking may contain other features or characters for internal lot control.

Bandpass Filter

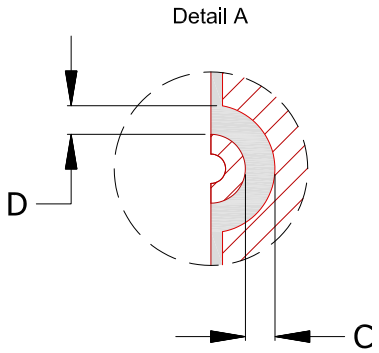
ABF-11R8G+

50Ω 10.6 to 13 GHz

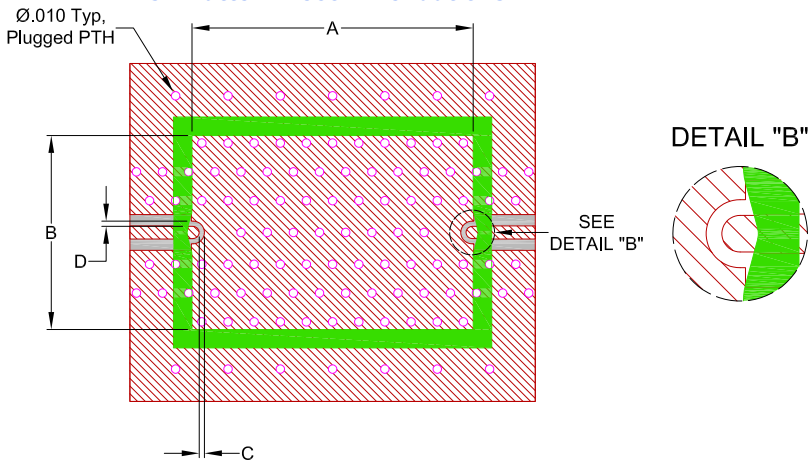
RECOMMENDED PCB LAYOUT PATTERN FOR FILTER



Filter RF I/O Detail
(Filter Back Side)



PCB Pattern Recommendations

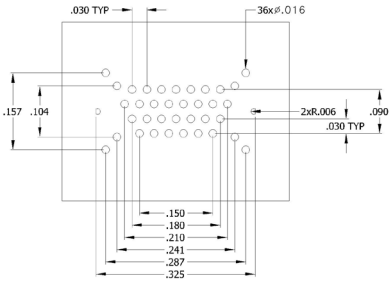


1) Customer PCB's ground pattern length (dimension A) can be similar to filter length.
2) Customer PCB's ground pattern width (dimension B) can be similar to filter width.
3) Dimensions C and D on Filter RF I/O detail and Customer PCB pattern can be closely match. The dimensions of C and D on the Customer PCB pattern can be slightly larger to account for component alignment tolerance (ground metal can be pulled back from RF I/O trace).
4) Recommend to use Solder mask at Customer PCB at outer area of filter pattern/ footprint with a clearance of about 1.25mil at each side. (Tighter registration tolerance required for solder mask)
5) Recommended to use Solder mask at I/O of Customer PCB as per above diagram (refer detail B).

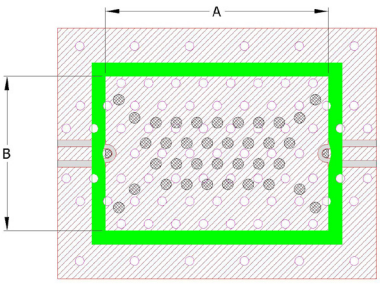
COMMENTS ON COMPONENT HANDLING AND SOLDER ATTACH

1) Avoid using soldering iron directly to the ceramic filter. This would lead to development of crack in the component due to thermal shock.
2) Vacuum pick-up tool or plastic tweezers are recommended for handling the components. Extra care should be taken not to scratch the filter or metal area.
3) Use 2-3 mil thickness stencil plate and screen print the solder. Refer below picture for recommended stencil pattern to get the best solder attachment.

Stencil opening drawing



Solder location after screen print



4) Plugged ground vias in the PWB will improve attachment consistency.
5) Recommended to have a similar or closer test board material and thickness (refer Mini-Circuits evaluation board for details) to minimize the CTE over the temperature range.

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ADDITIONAL DETAILED INFORMATION IS AVAILABLE ON OUR DASHBOARD. CLICK HERE

Performance Data and Graphs	Data Graphs S-Parameter (S2P Files) Data Set (.zip file) De-embedded to device pads
Case Style	UC2731 Lead Finish: Gold over Nickel Plate.
RoHS Status	Compliant
Tape and Reel	TR-F003
Suggested Layout for PCB Design	PL-764
Evaluation Board	TB-ABF-11R8G+
	Gerber File
Environmental Rating	ENV120

NOTES

A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuits' applicable established test performance criteria and measurement instructions.
C. The parts covered by this specification document are subject to Mini-Circuits' standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html

Thin-Film Bandpass Filter ABF-11R8G+

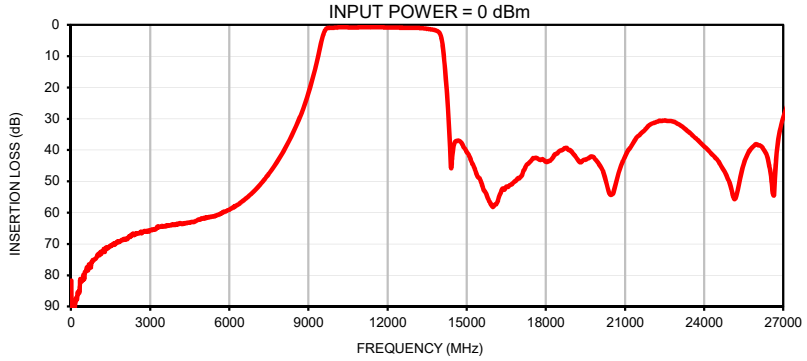
Typical Performance Data

FREQ. (MHz)	Insertion Loss (dB)	Input Return Loss (dB)	Output Return Loss (dB)
10	81.69	0.02	0.04
20	87.45	0.04	0.04
50	98.49	0.06	0.06
100	92.25	0.08	0.09
300	85.74	0.16	0.17
500	81.24	0.21	0.22
800	75.71	0.24	0.26
900	74.91	0.24	0.27
1000	73.54	0.24	0.27
2000	68.42	0.20	0.23
4000	63.77	0.32	0.34
6000	59.06	0.53	0.60
7000	52.62	0.66	0.67
8400	34.78	0.75	0.78
8650	30.06	0.74	0.81
9050	20.46	0.85	0.96
10000	0.89	16.65	16.71
10600	0.83	17.89	18.29
11000	0.77	22.32	21.78
11200	0.73	26.46	26.31
11400	0.72	31.56	32.61
11500	0.73	36.67	38.04
11800	0.79	30.39	30.55
11900	0.81	26.85	26.91
12000	0.83	24.66	24.68
12200	0.87	23.10	23.08
12400	0.89	25.50	25.78
12600	0.91	36.51	37.69
12800	0.94	25.80	25.77
13000	0.96	23.03	23.31
14000	3.02	15.22	15.40
15000	40.55	1.26	1.28
15500	49.23	1.29	1.28
16000	58.15	1.29	1.32
16500	51.70	1.26	1.33
17000	49.02	1.21	1.31
17500	42.68	1.20	1.32
18000	43.77	1.20	1.32
18500	40.40	1.27	1.35
19000	40.78	1.33	1.37
19200	42.96	1.34	1.38
19400	43.33	1.38	1.40
19500	43.06	1.40	1.41
19600	42.63	1.42	1.42
19700	42.06	1.44	1.44
19800	42.19	1.45	1.45
19850	42.71	1.45	1.45
20000	44.28	1.46	1.46
20100	45.61	1.46	1.47
20200	47.60	1.47	1.48
20400	53.66	1.50	1.51
20600	52.40	1.53	1.52
20800	46.24	1.53	1.55
21000	42.07	1.52	1.56
22000	31.65	1.53	1.68
23000	31.64	1.45	1.65
24000	38.83	1.47	1.62
25000	51.48	1.77	1.79
26000	38.16	2.18	2.08
27000	29.56	2.48	2.73

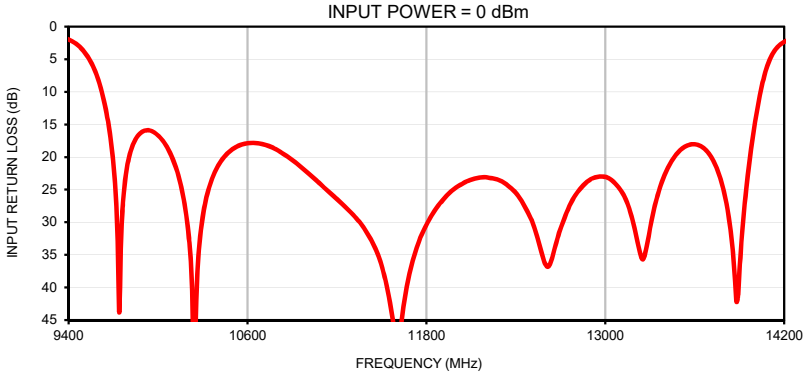
FREQ. (MHz)	Group Delay (ns)
10600	0.76
10650	0.76
10660	0.76
10670	0.76
10680	0.76
10690	0.75
10700	0.75
10710	0.75
10720	0.75
10730	0.75
10740	0.75
10800	0.75
10820	0.75
10840	0.75
10860	0.75
10880	0.75
10900	0.75
10920	0.75
10940	0.75
10960	0.75
10980	0.75
11000	0.75
11050	0.75
11100	0.75
11150	0.75
11180	0.75
11200	0.75
11250	0.75
11280	0.75
11300	0.75
11350	0.74
11400	0.75
11450	0.75
11500	0.75
11550	0.75
11600	0.75
11650	0.75
11700	0.75
11750	0.75
11800	0.75
11850	0.75
11900	0.75
12000	0.75
12050	0.76
12100	0.76
12200	0.76
12250	0.76
12300	0.77
12350	0.77
12400	0.77
12450	0.78
12500	0.78
12550	0.78
12600	0.79
12650	0.79
12700	0.80
12750	0.80
12800	0.81
12900	0.82
13000	0.83

Typical Performance Curves

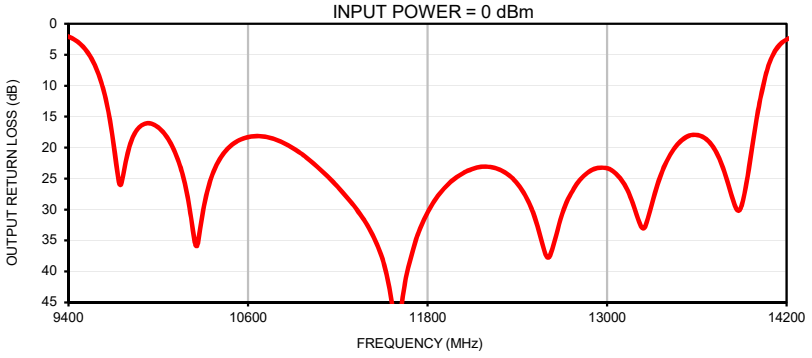
INSERTION LOSS
INPUT POWER = 0 dBm



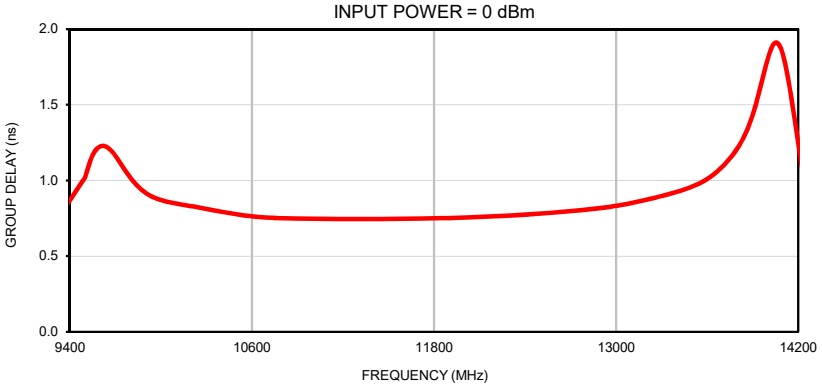
INPUT RETURN LOSS
INPUT POWER = 0 dBm



OUTPUT RETURN LOSS
INPUT POWER = 0 dBm

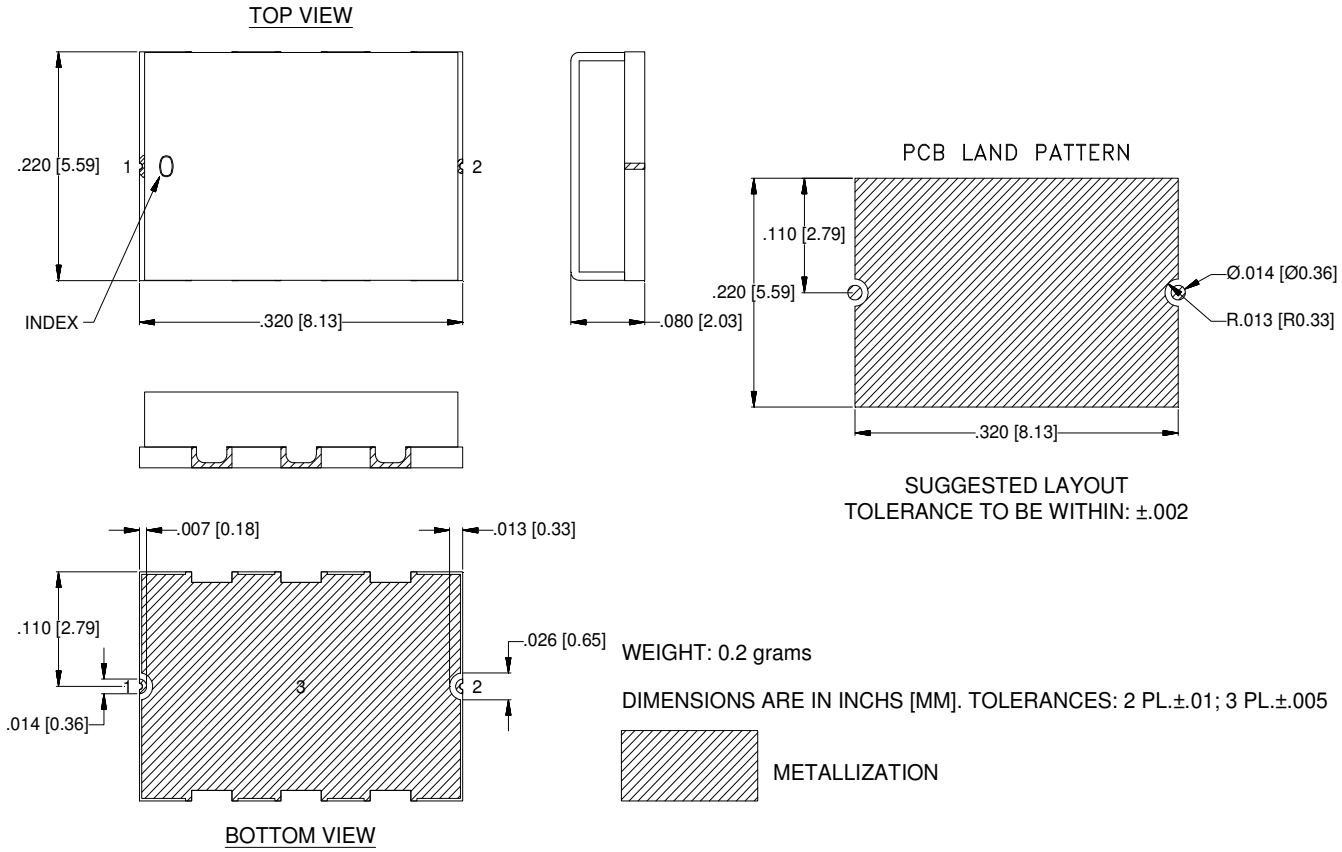


GROUP DELAY
INPUT POWER = 0 dBm



Case Style UC

Outline Dimensions UC2731

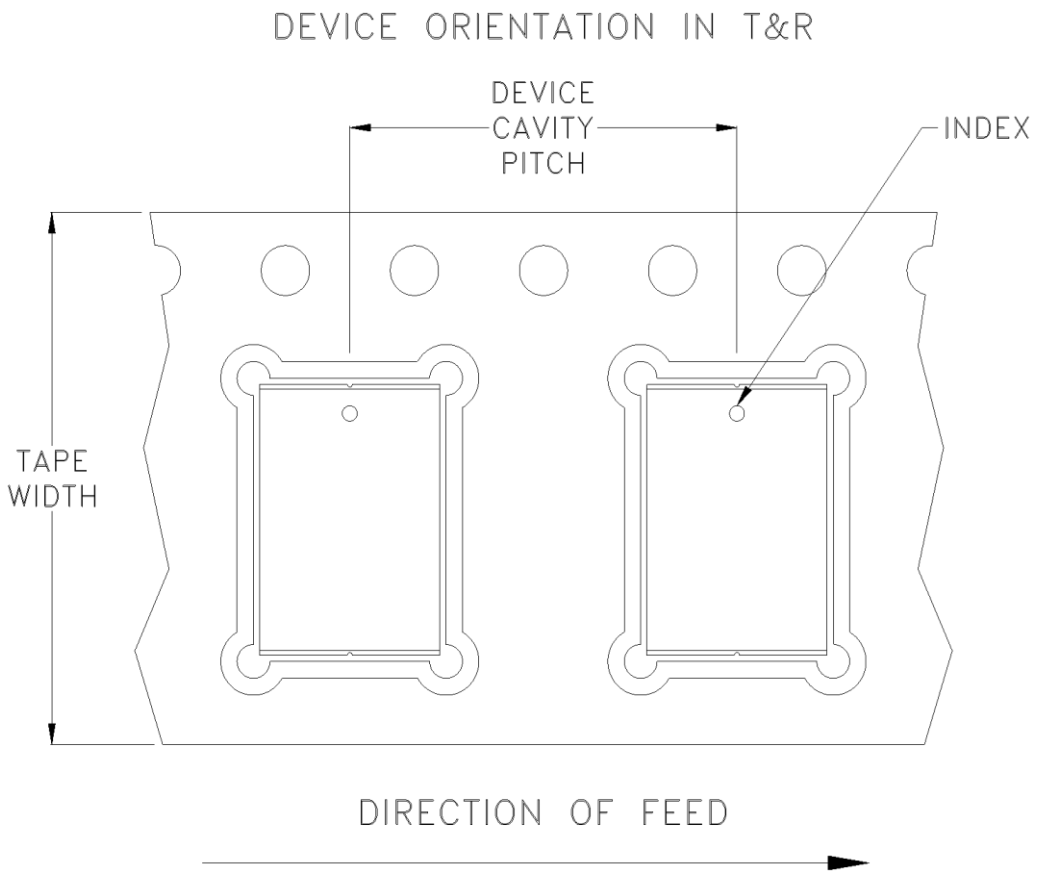


Notes:

1. Case material: Gold over Nickel over Annealed Stainless Steel.
2. Base: Ceramic
3. Termination finish: **as shown below or indicated on Data Sheet.**
   For RoHS Case Styles: Gold over Nickel plate. All models, (+) suffix.

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Tape & Reel Packaging TR-F003



Tape Width, mm	Device Cavity Pitch, mm	Real Size, inches	Devices per Reel See note
16	12	7	10
			20
			50
			100
			200
		13	500

Note: Please consult individual model data sheet/dashboard to determine device per reel availability.

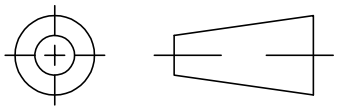
Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

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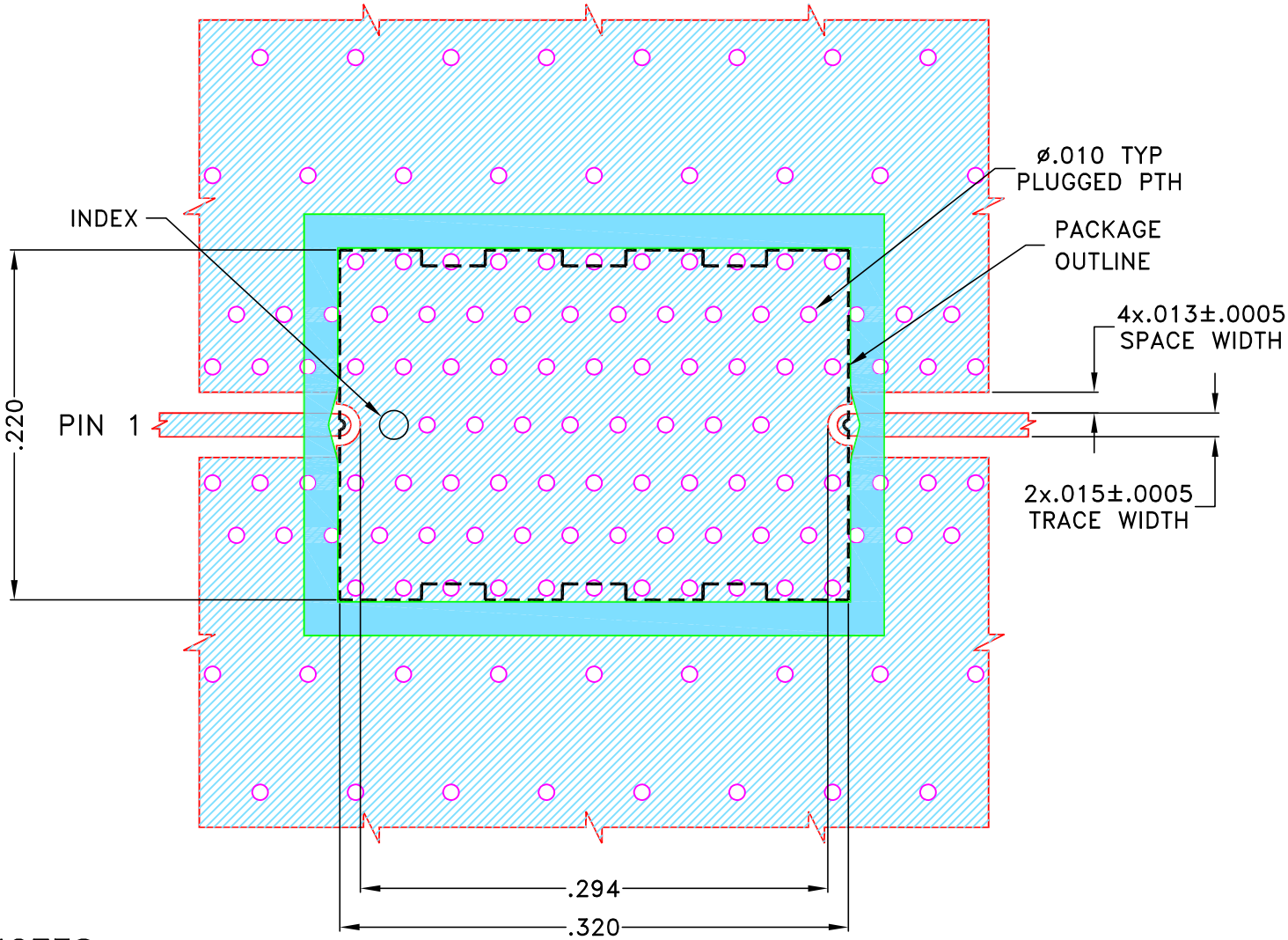
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THIRD ANGLE PROJECTION



REVISIONS					
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	NPO-003903	NEW RELEASE	OCT 23	LK	VC

SUGGESTED MOUNTING CONFIGURATION FOR UC2731 CASE STYLE



NOTES:

1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (RO4350B Lo Pro) WITH DIELECTRIC THICKNESS .0073±.0007. COPPER: 1/2 Oz. EACH SIDE.
   FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)

DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

UNLESS OTHERWISE SPECIFIED		INITIALS	DATE
DIMENSIONS ARE IN INCHES	DRAWN	LK	09 OCT 23
TOLERANCES ON:	CHECKED	MD	09 OCT 23
2 PL DECIMALS ±	APPROVED	RR	13 OCT 23
3 PL DECIMALS ± .005			
ANGLES ±			
FRACTIONS ±			

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ASHEETA1.DWG REV:A DATE:01/12/95

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Brooklyn NY 11235

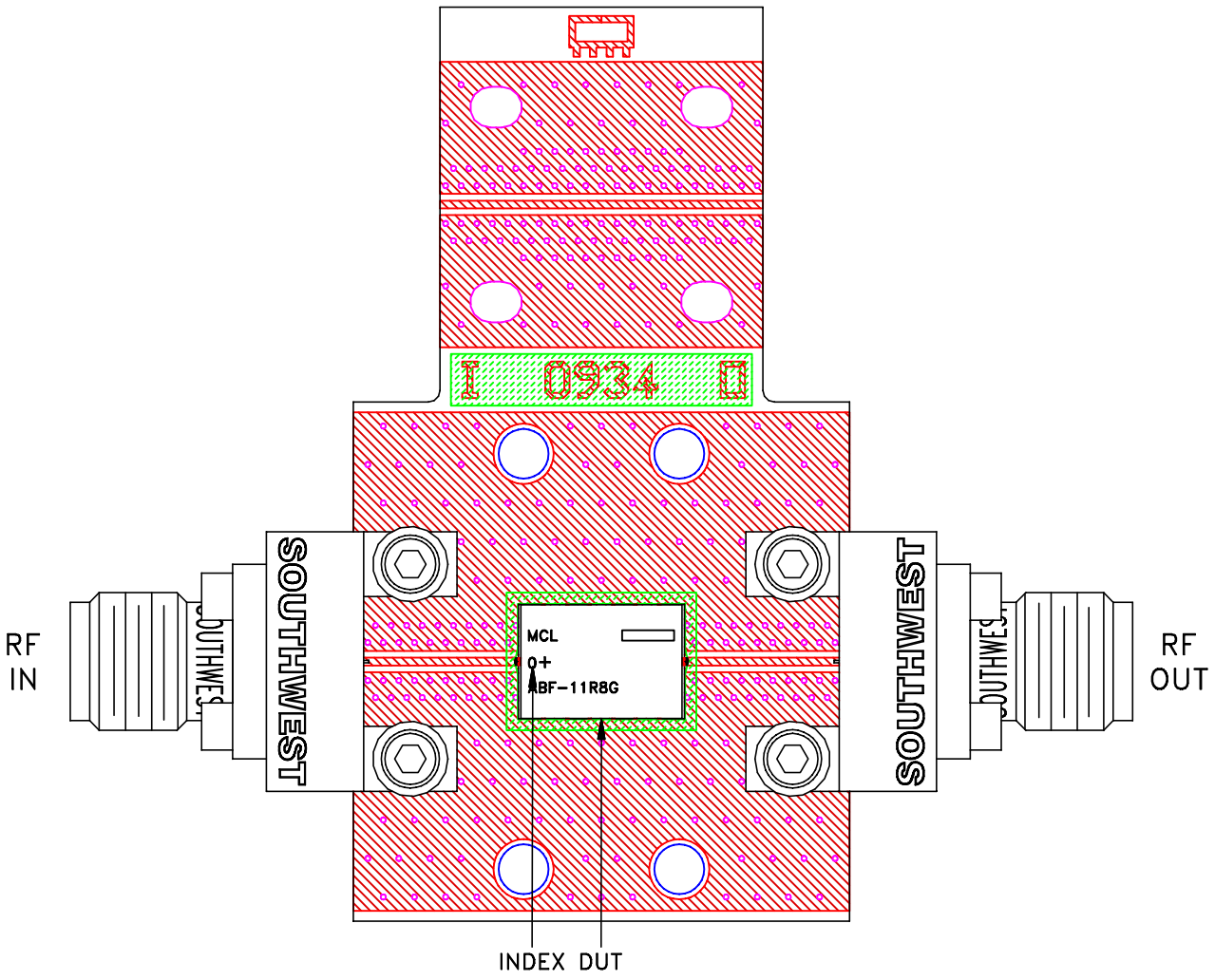
PL DWG, UC2731 C.S, 50 OHM, ALF

SIZE	CODE IDENT	DRAWING NO:	REV:
A	15542	98-PL-764	OR

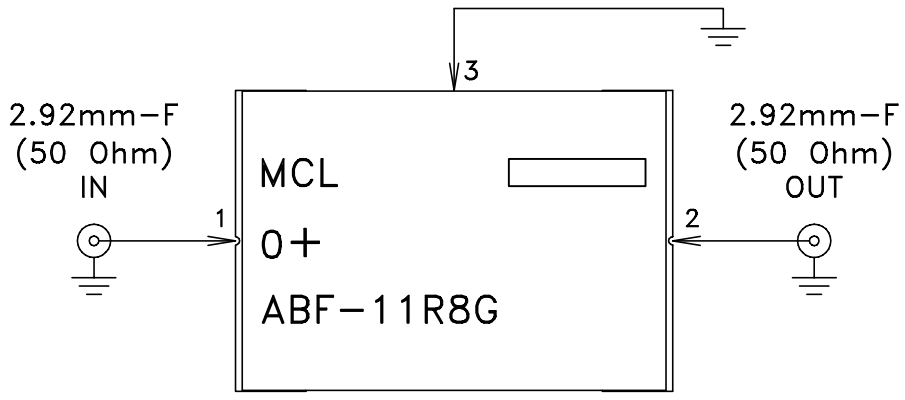
FILE:	SCALE:	SHEET:
98-PL-764	9.1:1	1 OF 1

Evaluation Board and Circuit

TB-ABF-11R8G+



Schematic diagram



Notes:

1. PCB Material: ROGERS (RO4350B Lo Pro) OR Equivalent, Dielectric Constant=3.48±.05
Dielectric Thickness: .0073±.0007 inch
2. 50 Ohm 2.92mm Female Connectors.

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Mini-Circuits

Environmental Specifications **ENV120**

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage
Thermal Shock	-55° to 125°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, Except +125°C

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